

规格书编号

**SPEC NO :**

# 产品规格书

# SPECIFICATION

CUSTOMER 客户: \_\_\_\_\_

PRODUCT 产品: SAW FILTER

MODEL NO 型号: HDBF19900B25

PREPARED 编制: \_\_\_\_\_ CHECKED 审核: \_\_\_\_\_

APPROVED 批准: \_\_\_\_\_ D A T E 日期: \_\_\_\_\_

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司  
Shoulder Electronics Limited



## 1. SCOPE

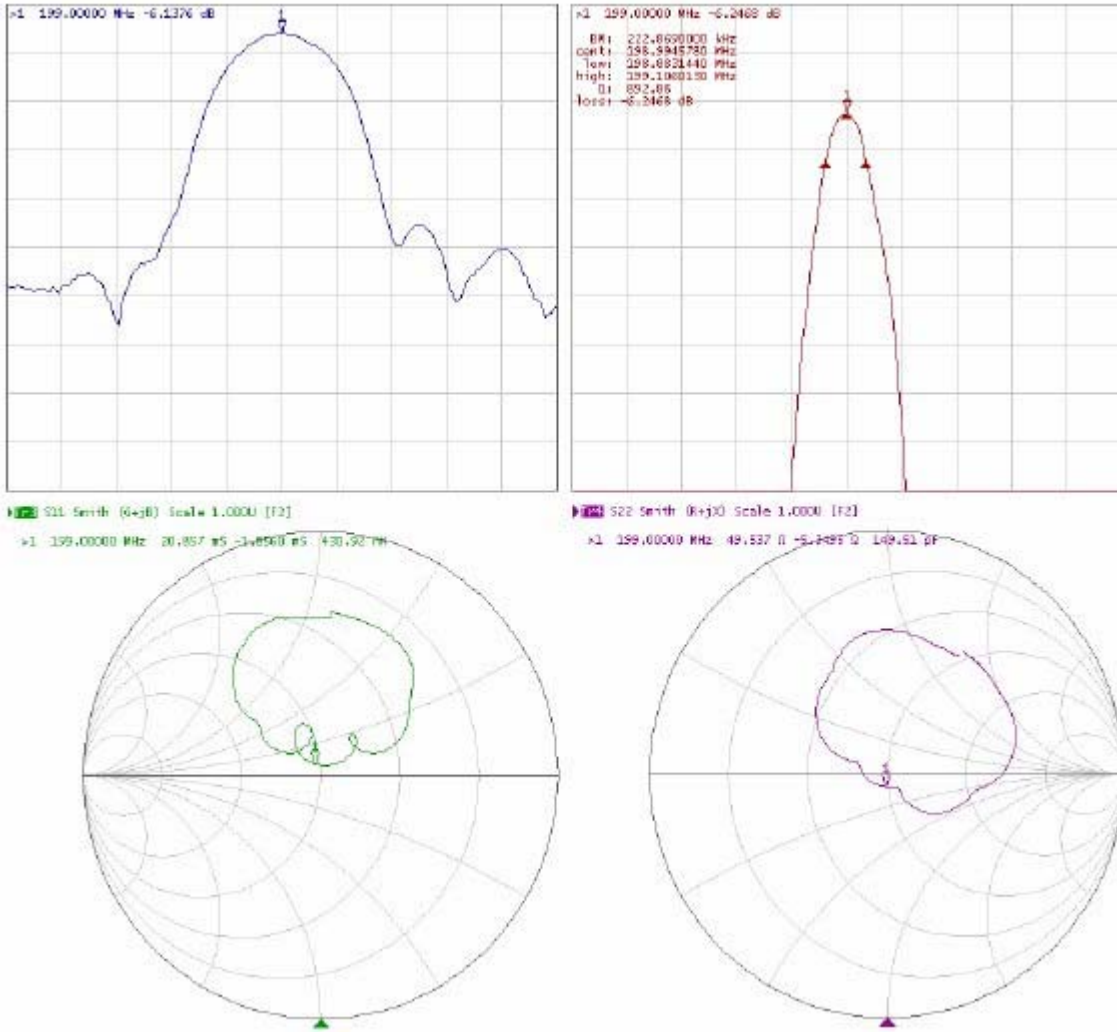
This specification shall cover the characteristics of SAW filter with HDBF19900B25 used for the page system.

## 2. ELECTRICAL SPECIFICATION

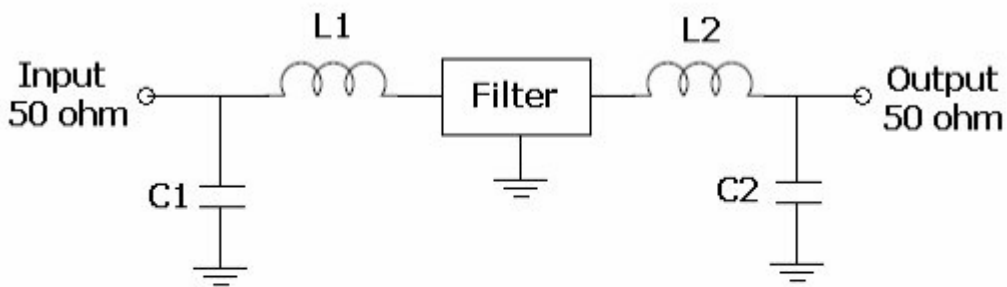
Maximum incident power in passband	+18dBm
Max.DC voltage between any 2 terminals	30VDC
Storage temperature range	-40°C to +85°C
Operation temperature range	-10°C to +85°C
Suitable for lead-free soldering-Max.soldering profile	260°C for 30s

### Electronic Characteristics

Parameter	Minimum	Typical	Maximum	Unit
Center Frequency	-	199.0	-	MHz
Insertion Loss	-	5.5	7.0	dB
1dB Bandwidth	± 100	± 140	-	KHz
Amplitude Ripple over $f_0 \pm 100\text{KHz}$	-	-	1.0	dB
$f_0-800$ to $f_0-600\text{KHz}$ and $f_0+600$ to $f_0+800\text{KHz}$	35	-	-	dB
119MHz to $f_0-800\text{KHz}$	45	-	-	dB
$f_0+800\text{KHz}$ to 278MHz	40	-	-	dB
Group Delay Variation over $f_0 \pm 100\text{KHz}$	-	300	500	nsec
Frequency Temperature coefficient	0.32			ppm/° C

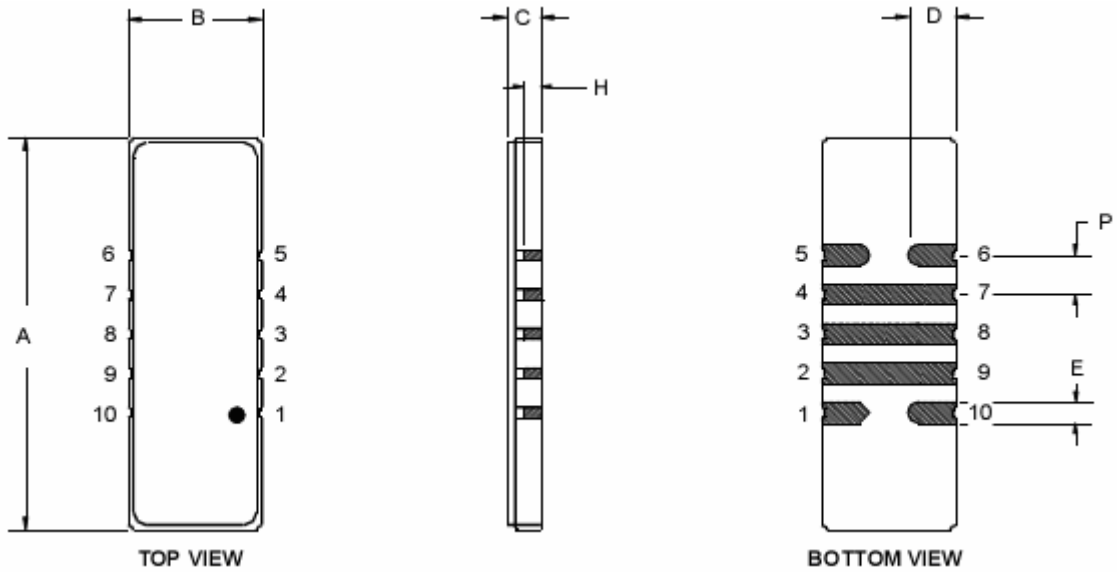


### 3. TEST CIRCUIT



L1 = 82 nH , L2 = 82 nH  
 C1 = 22 pF , C2 = 22 pF

**4.DIMENSION**



Dimension	mm		
	min	typ	max
A	18.8	19.0	19.2
B	6.3	6.5	6.7
C	1.58	1.76	1.94
D	2.15	2.3	2.45
E		1.02	
H	0.72	0.76	0.80
P		1.905	

Pin Configuration	
10	Input
5	Output
Other	Ground

## 5. ENVIRONMENTAL CHARACTERISTICS

### 5-1 Temperature cycling

Subject the device to a low temperature of  $-40^{\circ}\text{C}$  for 30 minutes. Following by a high temperature of  $+25^{\circ}\text{C}$  for 5 Minutes and a higher temperature of  $+85^{\circ}\text{C}$  for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in table 1.

### 5-2 Resistance to solder heat

Submerge the device terminals into the solder bath at  $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for  $10 \pm 1$  sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in table 1.

### 5-3 Solderability

Submerge the device terminals into the solder bath at  $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in table 1.

### 5-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in table 1.

### 5-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in table 1.

## 6. REMARK

### 6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

### 6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

### 6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.